

10/820747

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	228	(Je-hyoung with Ryu) (Sung-jin with Lee) (Jun-ho with Lee) (Tae-gyu with Kim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:41
L2	184331	samsung with electronics	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:41
L3	184370	1 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:42
L4	1806	3 and (test\$3 with (dut semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:42
L5	7	3 and (test\$3 with (dut semiconductor)) and ((heat with sink) radiator) and ((lead contact) with pusher) and (spring compress\$4 flexib\$4 resilient\$2 elastic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:56
L6	16	(test\$3 with (dut semiconductor)) and ((heat with sink) radiator) and ((lead contact) with pusher) and (spring compress\$4 flexib\$4 resilient\$2 elastic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:43
L7	6009	702/33-35,108,117,118,121,130-132,136,182.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:36
L8	66998	test\$3 with (dut semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:40
L9	626	7 and 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:50

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L10	184	7 and @pd>="20070309"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 17:58
L11	22	8 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:36
L12	11095	324/754-758,765.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:36
L13	5195	8 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:38
L14	6	6 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:38
L15	2042	702/118,182.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:40
L16	452	702/118,182.ccls.	US-PGPUB	OR	ON	2007/06/06 19:40
L17	9653	(test\$3 with (dut semiconductor)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:40
L18	15	16 and 17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:41
L19	150	(test\$3 with (dut semiconductor)) and ((heat with sink) radiat\$3) and ((lead contact) with push\$3) and (spring compress\$4 flexib\$4 resilient\$2 elastic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:44

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L20	4	5 and (thermal\$2 with pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:57
L21	3	5 and (thermal\$2 with pad).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/06 19:56